



Electrical Characteristics at T<sub>j</sub>
**XQOHVV RWKHUZLVH VSHFLILHG**
**Static Characteristics**

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250 mA	150	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250 mA	1	2	3	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =150V, T <sub>j</sub>	-	-	1	mA
		V <sub>GS</sub> =0V, V <sub>DS</sub> =150V, T <sub>j</sub>	-	-	100	
Gate to Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = 9V, V <sub>DS</sub> =0V	-	-	±100	nA
Drain to Source on Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	17.5	20	mΩ
Drain to Source on Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	20	25	mΩ
Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	-	65	-	S
Gate Resistance	R <sub>G</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> Open, f=1MHz	-	2.2	-	Ω

**Dynamic Characteristics**

Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =75V, f=1MHz	-	2105	-	pF
Output Capacitance	C <sub>oss</sub>		-	128	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	7	-	
Total Gate Charge	Q <sub>g</sub> (10V)	V <sub>DD</sub> =75V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	29	-	nC
Total Gate Charge	Q <sub>g</sub> (4.5V)		-	13	-	
Gate to Source Charge	Q <sub>gs</sub>		-	6	-	
Gate to Drain (Miller) Charge	Q <sub>gd</sub>		-	4	-	
Turn on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =75V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V, R <sub>G</sub> =10Ω	-	10	-	ns
Rise time	t <sub>r</sub>		-	8	-	
Turn off Delay Time	t <sub>d(off)</sub>		-	16	-	
Fall Time	t <sub>f</sub>		-	9	-	

**Reverse Diode Characteristics**

Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>F</sub> =20A	-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =75V, I <sub>F</sub> =20A, di <sub>F</sub> /dt=100A/μs	-	60	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	120	-	nC

Fig 1. Typical Output Characteristics

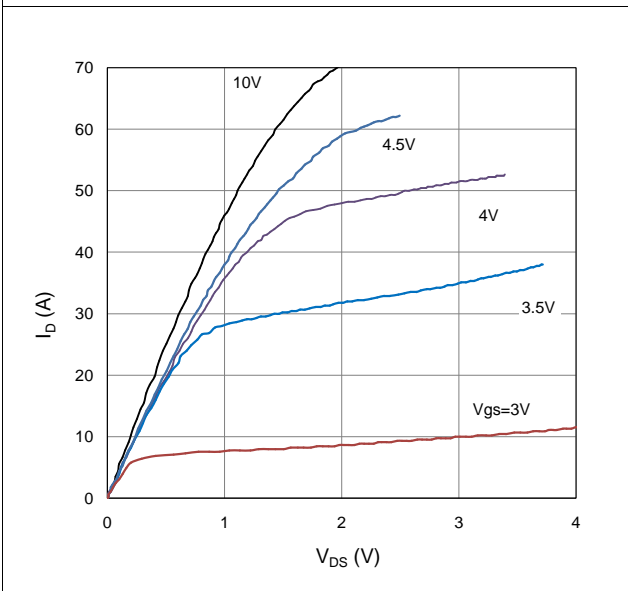


Figure 2. On-Resistance vs. Gate-Source Voltage

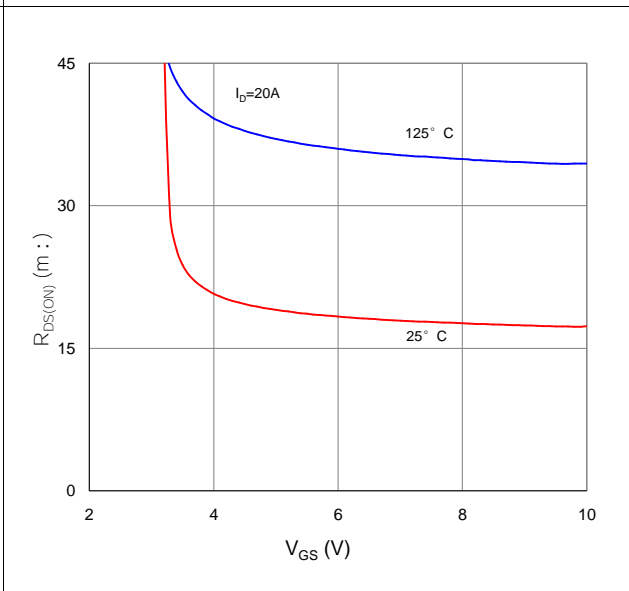


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

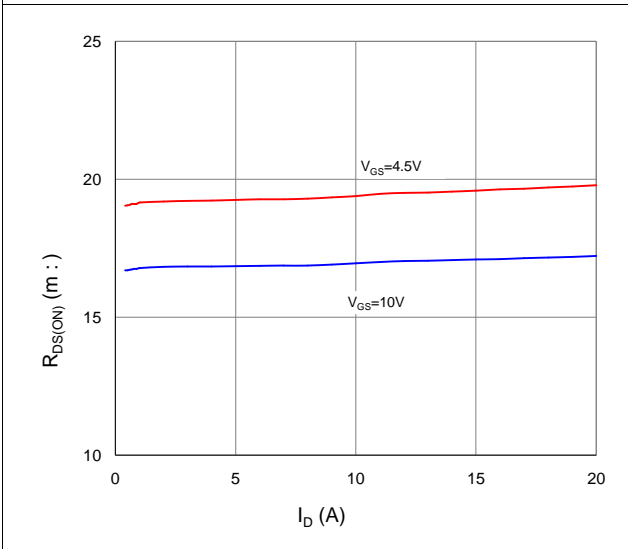


Figure 4. Normalized On-Resistance vs. Junction Temperature

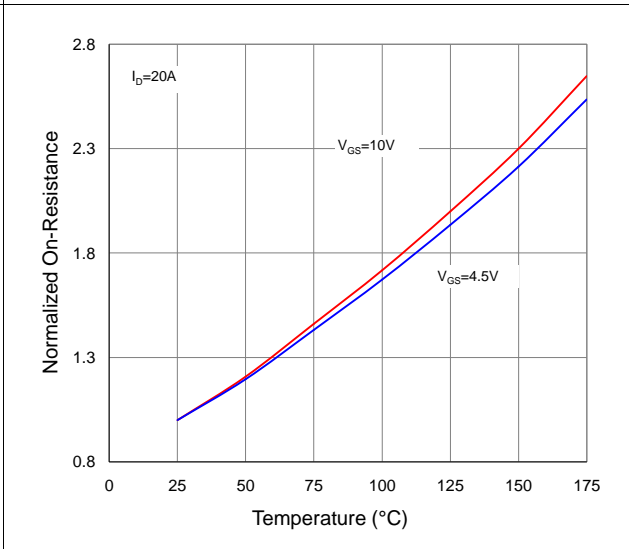


Figure 5. Typical Transfer Characteristics

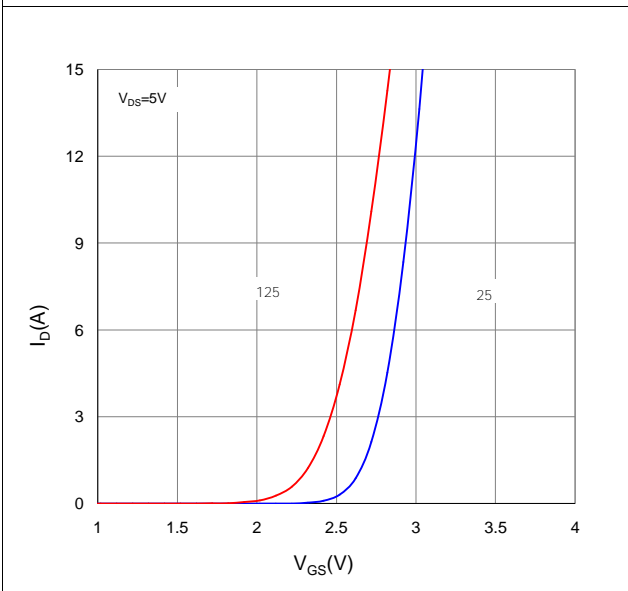


Figure 6. Typical Source-Drain Diode Forward Voltage

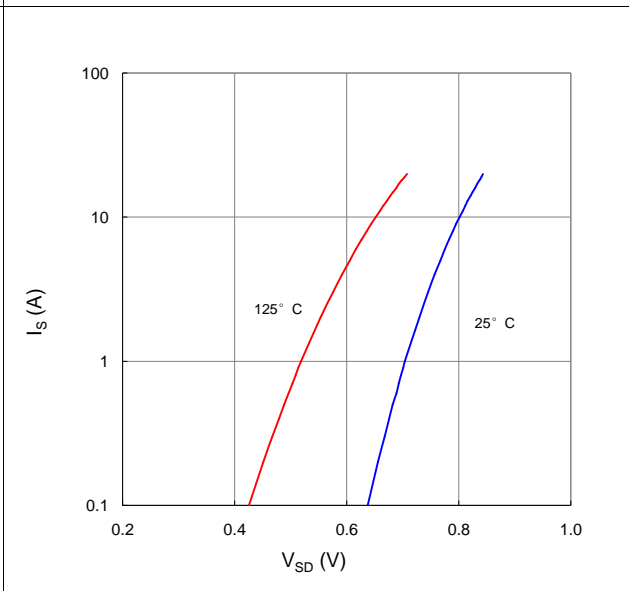
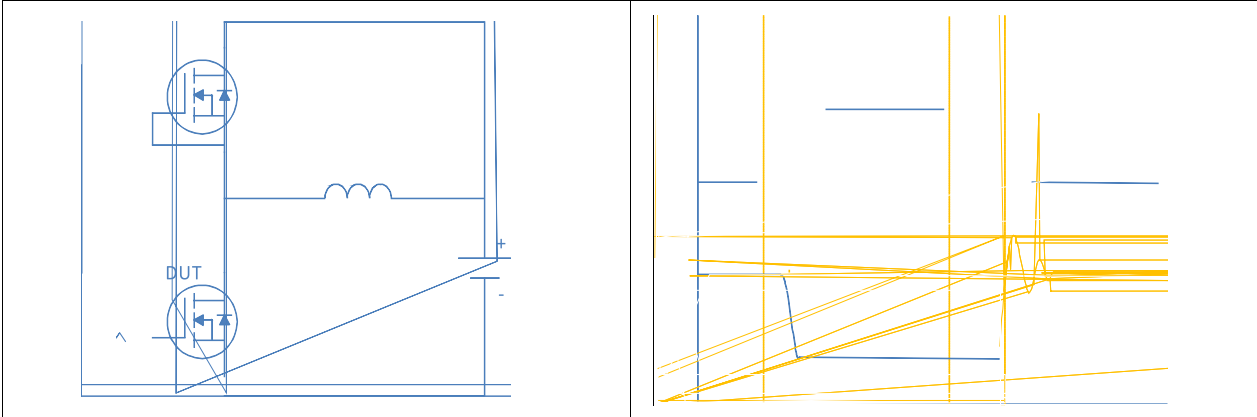


Figure 9. Maximum Safe Operating Area

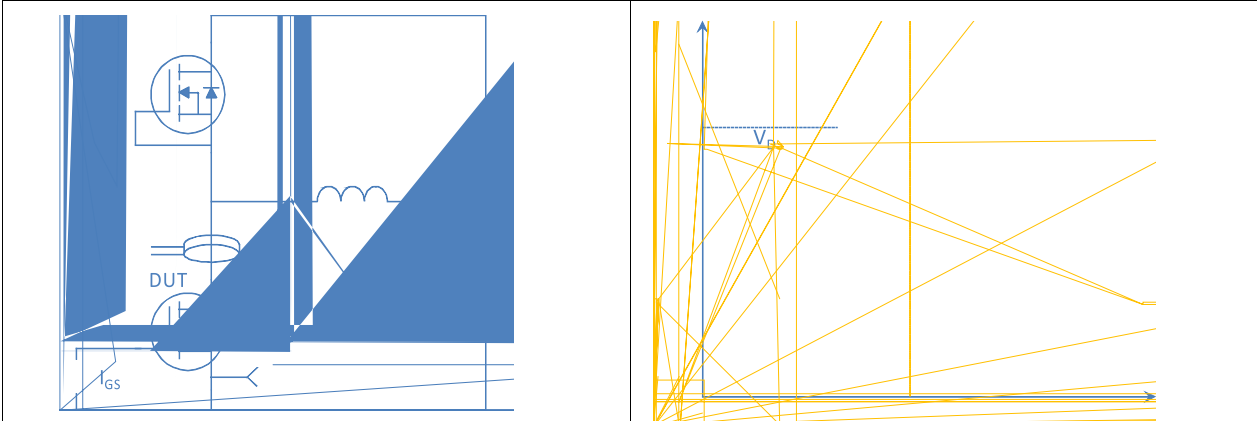
Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient

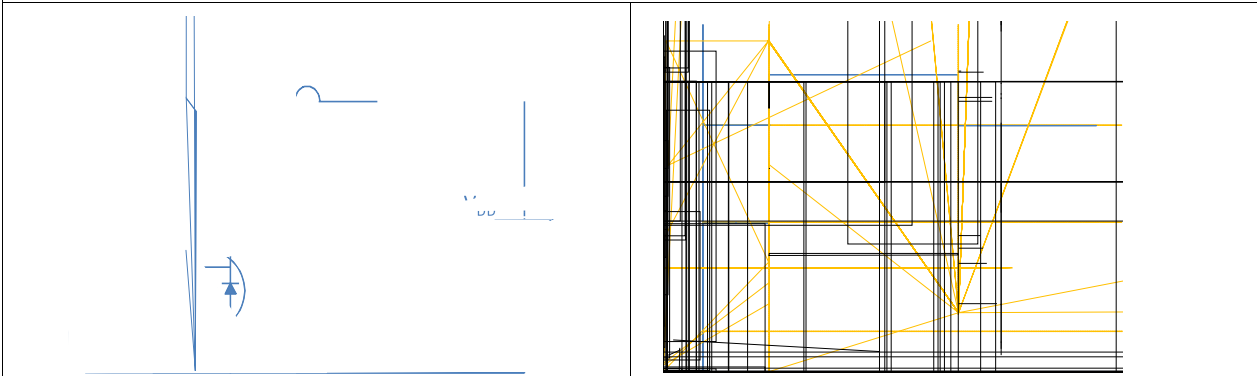
Inductive switching Test



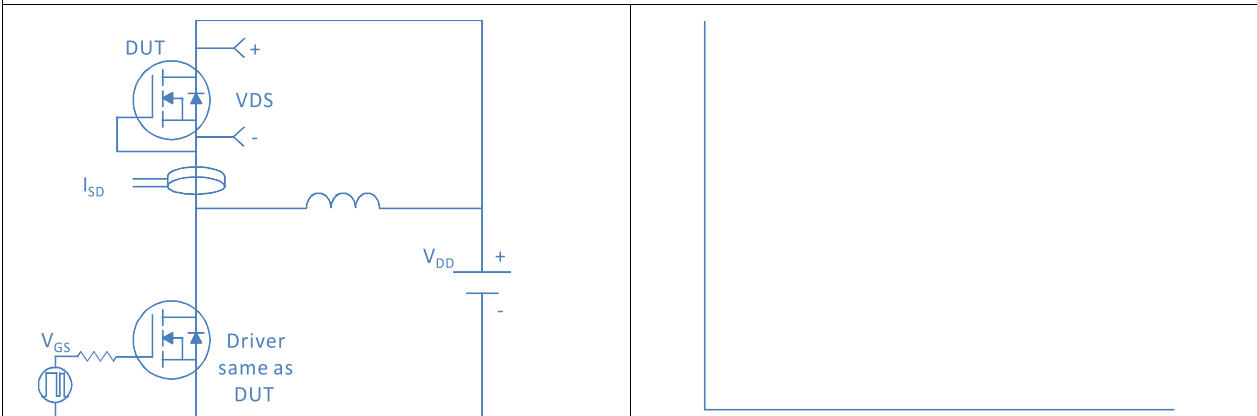
Gate Charge Test



Unclamped Inductive Switching (UIS) Test

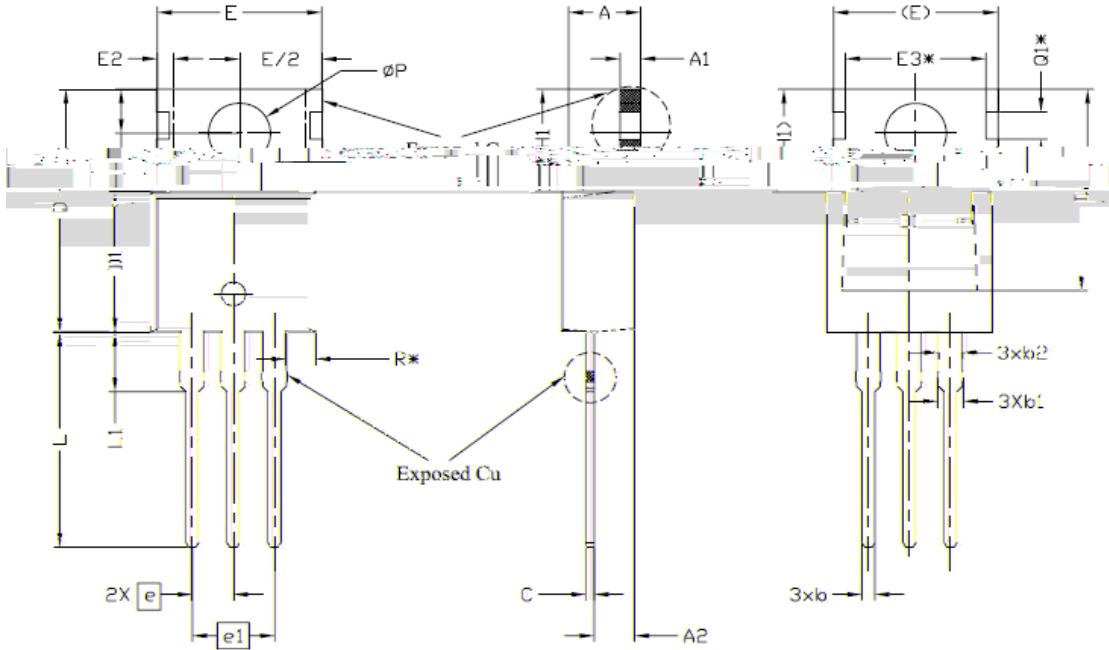


Diode Recovery Test



Package Outline

TO-220, 3 leads



SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A	4.25	4.84	5.81	
A1	1.16	1.27	1.60	
A2	2.76	2.80	2.75	
b	2.75	4.68	3.80	
b1	1.25	1.65	1.60	
b2	1.25	1.65	1.60	
e	3.15	4.15	5.70	
E	16.20	16.27	16.26	4
E2	4.80	5.40	5.15	
E3*	6.80	7.60	7.60	4, 5
E	6.80	7.60	7.60	4, 5
E1	4.80	5.40	5.15	4
E2			5.15	4
E3*		6.75	6.75	4
L		2.75	2.75	4
R		0.25	0.25	4
e		2.54	2.54	
e1		4.00	4.00	
b1	4.25	4.40	4.40	4, 5
b2	4.25	4.40	4.40	4, 5
b	4.25	4.40	4.40	4, 5
ØP	2.54	2.54	2.54	
3xb		1.27	1.27	
3xb1		1.27	1.27	
3xb2		1.27	1.27	